

# **S1000**

# (ULANSI:FR-4)Low Z-CTE

## **FEATURES**

- Lead-free compatible FR-4 Laminate.
- Tg(DSC)155℃,UV Blocking/AOI compatible.
- Excellent thermal reliability.
- Z-CTE 30~35% less than conventional FR-4.
- Excellent T/H reliability.
- Excellent anti-CAF and Q1000 performance.
- Low water absorption.

## **APPLICATIONS**

Computer, Instrumentation, VCR, communication equipment, automotive electronics, electronic game machine, and etc.

# **GENERAL PROPERTIES**

| Test Item          |                     | T                         | 1114                 | Property Data    |                     |  |
|--------------------|---------------------|---------------------------|----------------------|------------------|---------------------|--|
|                    |                     | Treatment Condition       | Unit                 | SPEC             | Typical Value       |  |
| Tg                 |                     | DSC                       | $^{\circ}\mathbb{C}$ | ≥150             | 155                 |  |
| Flammability       |                     | C-48/23/50                | Rating               | V-0              | V-0                 |  |
|                    |                     | E-24/125                  | rtating              |                  |                     |  |
| Volume Resistivity |                     | After moisture resistance | MΩ-cm                | ≥10 <sup>6</sup> | 7.4×10 <sup>8</sup> |  |
| Volumer            | Colotivity          | E-24/125                  | IVI 32 -CIII         | ≥10 <sup>3</sup> | 5.6×10 <sup>6</sup> |  |
| Surface F          | Pocietivity         | After moisture resistance | $M\Omega$            | ≥10 <sup>4</sup> | 7.6×10 <sup>7</sup> |  |
| Surface            | Resistivity         | E-24/125                  |                      | ≥10 <sup>3</sup> | $2.8 \times 10^{6}$ |  |
| Arc Resi           | stance              | D-48/50+D-0.5/23          | S                    | ≥60              | 147                 |  |
| Dielectric I       | Breakdown           | D-48/50+D-0.5/23          | KV                   | ≥ 40             | 45                  |  |
| Dielectric         | Constant<br>(1MHz)  | C-24/23/50                | -                    | ≤ 5.4            | 4.9                 |  |
| Dissipation        | on Factor<br>(1MHz) | C-24/23/50                | -                    | ≤ 0.035          | 0.011               |  |
| Thermal            | Unetched            | 288℃,solder dip           | _                    | >10s             | 100s                |  |
| Stress             | Etched              | ,                         | _                    | No delamination  | No delamination     |  |
| Peel               | 1oz                 | 288℃,10s                  | N/mm                 | ≥1.05            | 1.4                 |  |
| Strength           | Cu. Foil            | <b>125</b> ℃              | IN/IIIIII            | ≥ 0.70           | 1.2                 |  |
| Flexural           | LW                  | A                         | MPa                  | ≥ 415            | 540                 |  |
| Strength           | CW                  | 7                         |                      | ≥ 345            | 450                 |  |
| Water Abs          | •                   | D-24/23                   | %                    | ≤ 0.5            | 0.09                |  |
| CTE                | Before Tg           | TMA                       | PPM/℃                | ≪60              | 49                  |  |
|                    | After Tg            | TMA                       | PPM/℃                | ≪300             | 250                 |  |
| Z-axis             | 50~260℃             | TMA                       | %                    | ≤3.5             | 3.4                 |  |
| Td                 |                     | 10℃/min,N₂                | $^{\circ}\mathbb{C}$ | ≥325             | 335                 |  |
| T288               |                     | TMA                       | min                  | ≥5               | 10                  |  |
| T260               |                     | TMA                       | min                  | ≥30              | 60                  |  |
| CTI                |                     | IEC60112                  | V                    | PLC 3(175V249V)  | PLC 3               |  |

Remarks: 1.Specification sheet:IPC-4101/99, is for your reference only.

 $Explanations: \quad C = Humidity conditioning; \ D = Immersion conditioning in distilled water; \ E = Temperature conditioning.$ 

<sup>2.</sup>All the typical value is based on the 1.6mm specimen, while the Tg is for specimen  $\geqslant$  0.50mm.

<sup>3.</sup>All the typical value listed above is for your reference only, please turn to Shengyi Technology Co., Ltd. for detailed information, and all rights from this data sheet are reserved by Shengyi Technology Co., Ltd.

The figures following the letter symbols indicate with the first digit the duration of the preconditioning in hours, with the second digit the preconditioning temperature in °C and with the third digit the relative humidity.



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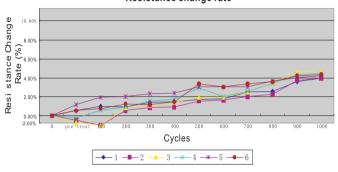
#### ■ Thermal Change Test - Q1000

A) Pre-Treatment:

 $^{'}$ 125  $^{\circ}$ C/ 2hour in the oven.

- B) Thermal shock condition:
  - -40 °C(30min)~+125 °C(30min),transfer time<2min.

#### Resistance change rate



## ■ Micro-section after Q1000

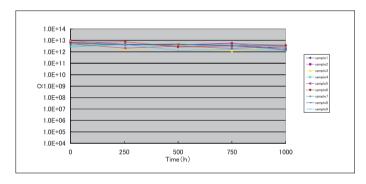


■Test Sample



X200 micro-section X50 micro-section

# ■ Anti-CAF Test



Specimen: Pitch=0.7mm,  $\phi$  =0.25mm, DC50V/85 $^{\circ}$ C/85 $^{\circ}$ RH

## ■ PCT( High Pressure Cooker Test)

| PCT (E-121℃/105KPa)  | Solder Dipping@288℃/10 s |       |  |  |
|----------------------|--------------------------|-------|--|--|
| PCI (E-121 C/103KPa) | Standard FR-4            | S1000 |  |  |
| 30 min               | OK                       | OK    |  |  |
| 60 min               | OK                       | OK    |  |  |
| 120 min              | NG                       | OK    |  |  |

Specimen: 1.6mm(uncladding) 100mm\*100mm

## **PURCHASING INFORMATION**

| Thickn           | ess | Copper foil          | Standard Size  |                        |  |  |
|------------------|-----|----------------------|--|------------------------|--|--|
| 0.05r<br>to 3.2r |     | 12 μ m<br>to 105 μ m | 1,020×1,220mm (40" ×48" )<br>1,070×1,220mm (42" ×48" ) | 915×1,220mm (36" ×48") |  |  |

- \* Other sheet size and thickness could be available upon request.
- \* UL认可单、双面PCB板,最小厚度0.38mm。



# S1000B PREPREG

# (ULANSI:FR-4) Bonding Prepreg For S1000

## **FEATURES**

- Low Z- CTE.
- Excellent chemical resistance.
- Excellent adhesion property and PCB processability.
- UV Blocking /AOI compatible.

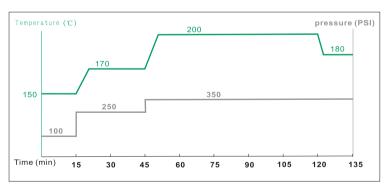
## PREPREG PARAMETERS

| Designation | Glass fabric | Performance   | Gel time |      |                 | Cured Thickness |                |
|-------------|--------------|---------------|----------|------|-----------------|-----------------|----------------|
|             | type         | 1 CHOIIIIance | (sec)    | (%)  | (%)             | ( µ m)          | (roll type)    |
|             | 106          | Low<br>Z-CTE  | 115±20   | 73±3 | 37±5            | 50±10           |                |
|             | 106LD        |               |          | 73±3 | $37\pm5$        | 50±10           |                |
|             | 1078LD       |               |          | 67±3 | $34\pm 5$       | 78±10           |                |
| S1000B      | 1080         |               |          | 67±3 | $34\pm5$        | 78±10           | 1,260mm×114.3m |
| 310000      | 2313         |               |          | 58±3 | $26\pm5$        | 100±15          | (125yards)     |
|             | 2116         |               |          | 55±3 | $26\pm5$        | 120±15          |                |
|             | 1500         |               |          | 48±3 | 48±3 22±5 160±1 | 160±15          |                |
|             | 7628         |               |          | 46±3 | 21±5            | 195±20          |                |

# Type, Resin Content and Size Could be Available Upon Request Prepreg Test Method

• Resin Content, Resin Flow, Gel Time: IPC-TM-650

#### HOT PRESSING CYCLE



Heat-up rate:  $1.0 \sim 2.5 \, ^{\circ}\text{C/min} (80 \sim 140 \, ^{\circ}\text{C})$ Curing time:  $>45 \, ^{\circ}\text{min} (180 \sim 190 \, ^{\circ}\text{C})$ 

The hot pressing parameters is for your reference only, please turn to

Shengyi Technology Co., Ltd for detailed information.

#### STORAGE CONDITION

- ullet Three months when stored at <23°C and <50% RH .
- Beware of moisture, always keep wrapped in damp-proof material. Were kept in normal condition, prepreg
  might absorb moisture and its bonding strength would be weakened.
- Avoid UV-rays and strong light.